Flexible Circuits: Project Scope Presentation

"Flexible circuits are a high-growth technology in the area of electrical interconnectivity and look set to deliver improved performance against the demands of many 21st century products... flexible printed circuits have replaced hand-built wire harnesses in many applications."

> Peter Macleod, Flexible Circuit Technology Prime Faraday Technology Watch

What is diabetes?

A metabolic disease in which the body's inability to produce any or enough insulin causes elevated levels of glucose in the blood.

If not controlled, diabetes can produce complications that can affect nearly every organ in the body:

- heart attack
- stroke
- atherosclerosis
- high blood pressure
- neuropathy
- nephropathy

- cataracts and glaucoma
- foot damage and possible limb amputation
- hearing impairment
- skin conditions
- Alzheimer's disease



Glucose Monitoring

For some people, it is necessary to monitor their blood glucose levels daily—and sometimes more than once a day!

Fact: Glucose levels can be also measured in other corporal (human body) fluids...

Knowing this... Could an alternative to the annoying pinching procedure be developed?

Example Idea: Smart Lens



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- The lens can measure blood sugar levels directly from tear fluid on the eyeball surface
- It contains a low-power microchip and an almost invisible, hair-thin electronic flexible circuit
- The system sends data to a mobile device to keep the person informed.

Flexible Electronics

At the core of the Google smart lens is a thin and flexible printed circuit

"A flexible printed circuit is a patterned arrangement of printed circuitry and components that uses a flexible base material with or without a flexible cover lay." —IPC, Association Connecting Electronics Industries

Flexible Circuit Composition

flexible circuit =

dielectric substrate film (base material) ╋ electrical conductors (circuit traces) protective finish (cover coat) adhesives (bond materials)

Flexible Circuit Composition

Substrate materials:

- **Polyesters:** Low cost and highly flexible
- Polymides: high-temperature characteristics (~700 °C) and low thermal expansion

Electrical conductors:

- Gold, aluminum, nickel or silver, but mainly copper
- Ink loaded with carbon or silver particles

Flexible Circuit Composition

Single-Sided Flexible Circuits

- Most common type
- Single conductor layer on a flexible dielectric film
- Access to circuit-termination from one side only
- With or without cover lays and protective coatings
- Simple design; highly cost effective
- Best suited to dynamic-flexing

Flexible Circuits Composition Single-Sided Flexible Circuits



Adhesive

Conductor



Cleaning

Impurities

Sputter Deposition Photolithography

Photoresist

Photoresist

Removal

UV Ligth Exposure

Etching

Stripping

The UV light exposure step in the photolithography process is the core of the research performed for this lesson. Note that the circuit mask is placed over the wafer coated with the photoresist. Challenge question: Is it expected that that the printed circuit is an exact **UV** Source copy of the mask, or is an alteration produced by the Mask pass of the UV light **Photoresist Coat** through the photoresist Conductor coat? Or, is the diffraction Glass + Polymide of the light in this coating significant?

To answer this question, we must compare the dimensions of a circuit in the original mask, and the dimensions of the final circuit obtained through the photolithography process.





We will take samples of measurements from two sets of pictures: original circuits on masks and their corresponding printed circuits.

We will use a special graph interface created in GeoGebra to perform these measurements



We will use statistical analysis, hypothesis testing for differences, to conclude if the differences in dimensions mask-printed circuits are statistically significant or not.

A T-test is the correct approach for dependent or independent samples



We'll put the measurements from the diffe

We'll put the measurements from the different circuits together in a relative size change graph

We'll use the equation:



dependent variable *y* of the graph



Taking logarithm of the y variable, a linear relationship can be found. Solving for y, an empirical relationship for the relative change can be obtained.

With this equation, it is possible to predict the change in the printed circuit as a function of the original dimensions



Suggested reading:

- Photolithography: <u>http://en.wikipedia.org/wiki/Photolithography</u>
- What is photolithography: <u>http://whatis.techtarget.com/definition/photolithography</u>
- Carl Batt: Photolithography: <u>http://www.youtube.com/watch?v=9x3Lh1ZfggM</u>
- Semiconductor Lithography. The Basic Process: <u>http://www.lithoguru.com/scientist/lithobasics.html</u>
- What Else Could Smart Contact Lenses Do?: <a href="http://www.technologyreview.com/news/529196/what-else-could-smart-contact-lenses-do/smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-lenses-do-smart-contact-smart-s
- Google's Prototype "Smart Contact Lens": Measuring Blood Glucose Levels for People with Diabetes: http://www.visionaware.org/blog/visionaware-blog/googlesprototype-smart-contact-lens-measuring-blood-glucose-levels-forpeople-with-diabetes-1418/12

Custom Custom Shows

Photolithography

Sputter Deposition

A method of depositing thin films by way of eroding material from a "target" source onto a "substrate."

Typically accomplished by bombarding the "target" (that is, the source of deposition material) with atoms of inert gas.

The momentum of the bombarding atoms transfers to target atoms enabling them to separate from the target flying towards the deposition surface.



Substrate and film growth

Cleaning Impurities

Photolithography

Cleaning Impurities

Organic / inorganic contaminations are usually removed by wet chemical treatment using solutions containing hydrogen peroxide.

Other solutions made with trichloro-ethylene, acetone or methanol may also be used to clean



Photolithography

Photoresist

Photoresist Coating

A UV light-sensitive liquid that loses its resistance (its susceptibility to attack by an etchant or solvent) when exposed to UV light.

A wafer coated with a thin conductor, is covered with photoresist by spin coating; this viscous liquid solution is dispensed onto a rapidly spun wafer, to produce a uniformly thick layer.



Photolithography

UV Ligth Exposure

UV Light Exposure

UV light passes through a mask (a print of the circuit to be transferred to the wafer) placed on the conductor coated wafer. Light causes a chemical change on the photoresist. Positive photoresist becomes soluble in the developer when exposed; with negative photoresist, unexposed regions are soluble in the developer.





Photolithography

Photoresist Photoresist Removal

Photoresist Removal

After a photoresist is no longer needed, it must be removed from the substrate

This usually requires a liquid resist stripper or developer that chemically alters the resist so that it no longer adheres to the substrate



Photolithography

Etching

Etching

A liquid ("wet") or plasma ("dry") chemical agent is used to remove the uppermost layer of the substrate in the areas that are not protected by photoresist

Stripping

Photolithography

Stripping

The use of a solvent called a *stripper* to remove the photoresist and any of its residues

